



Product Change Notification: JPZA-12DMFE808

Date:

15-Oct-2026

Product Category:

Digital Potentiometers, Inductive Position Sensors, LIN Transceiver With Vreg, Linear Op Amps

Notification Subject:

CCB 8449 Initial Notice: Qualification of CRM-1064L as an additional die attach material, palladium coated copper with gold flash (CuPdAu) as an additional wire material, and G630AY as an additional mold compound material for selected LX34211, MCP2022A, MCP6H74, MCP45HV31, MCP6H04, MCP6H94, MCP41HV31, MCP45HV51 and MCP41HV51 device families available in 14L TSSOP (4.4mm) package at MMT assembly site.

Affected CPNs:

[JPZA-12DMFE808_Affected_CPN_10152026.pdf](#)

[JPZA-12DMFE808_Affected_CPN_10152026.csv](#)

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of CRM-1064L as an additional die attach material, palladium coated copper with gold flash (CuPdAu) as an additional wire material, and G630AY as an additional mold compound material for selected LX34211, MCP2022A, MCP6H74, MCP45HV31, MCP6H04, MCP6H94, MCP41HV31, MCP45HV51 and MCP41HV51 device families available in 14L TSSOP (4.4mm) package at MMT assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change
Assembly Site	Microchip Technology	Microchip Technology Thailand (Branch) (MMT)	No

	Thailand (Branch) (MMT)			
Wire Material	Au	Au	CuPdAu	Yes
Die Attach Material	QMI519 (PFAS-free)	QMI519 (PFAS-free)	CRM-1064L (PFAS-free)	Yes
Molding Compound Material	G600V	G600V	G630AY	Yes
Lead-Frame Material	C7025	C7025		No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying CRM-1064L as an additional die attach material, palladium coated copper with gold flash (CuPdAu) as an additional wire material, and G630AY as an additional mold compound material at MMT assembly site.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: December 2026

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

	October 2026					>	December 2026				
Work Week	40	41	42	43	44		49	50	51	52	53
Initial PCN Issue Date			x								
Qual Report Availability								x			
Final PCN Issue Date								x			

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: October 15, 2026: Issued initial notification

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_JPZA-12DMFE808_Qual Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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